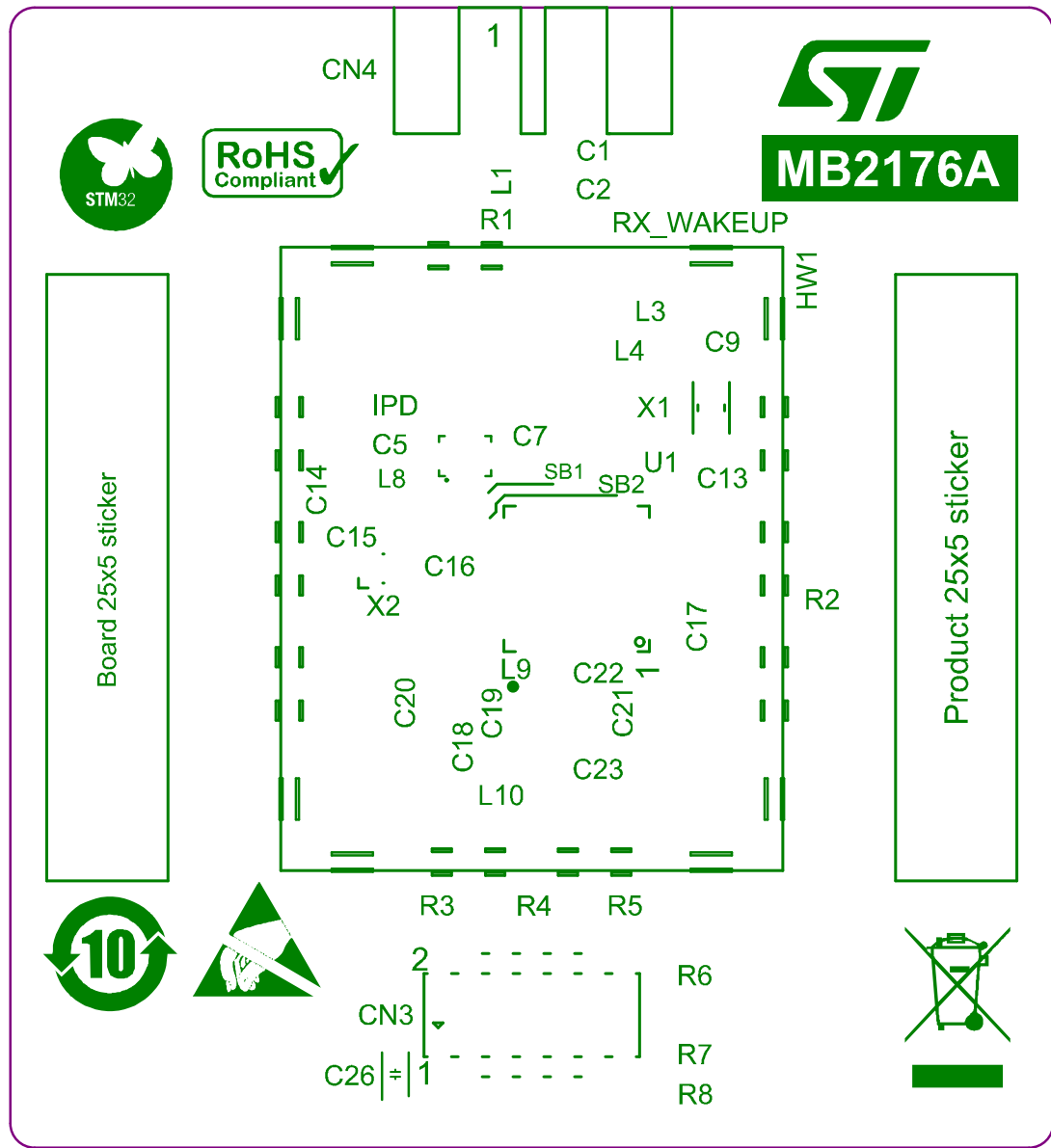
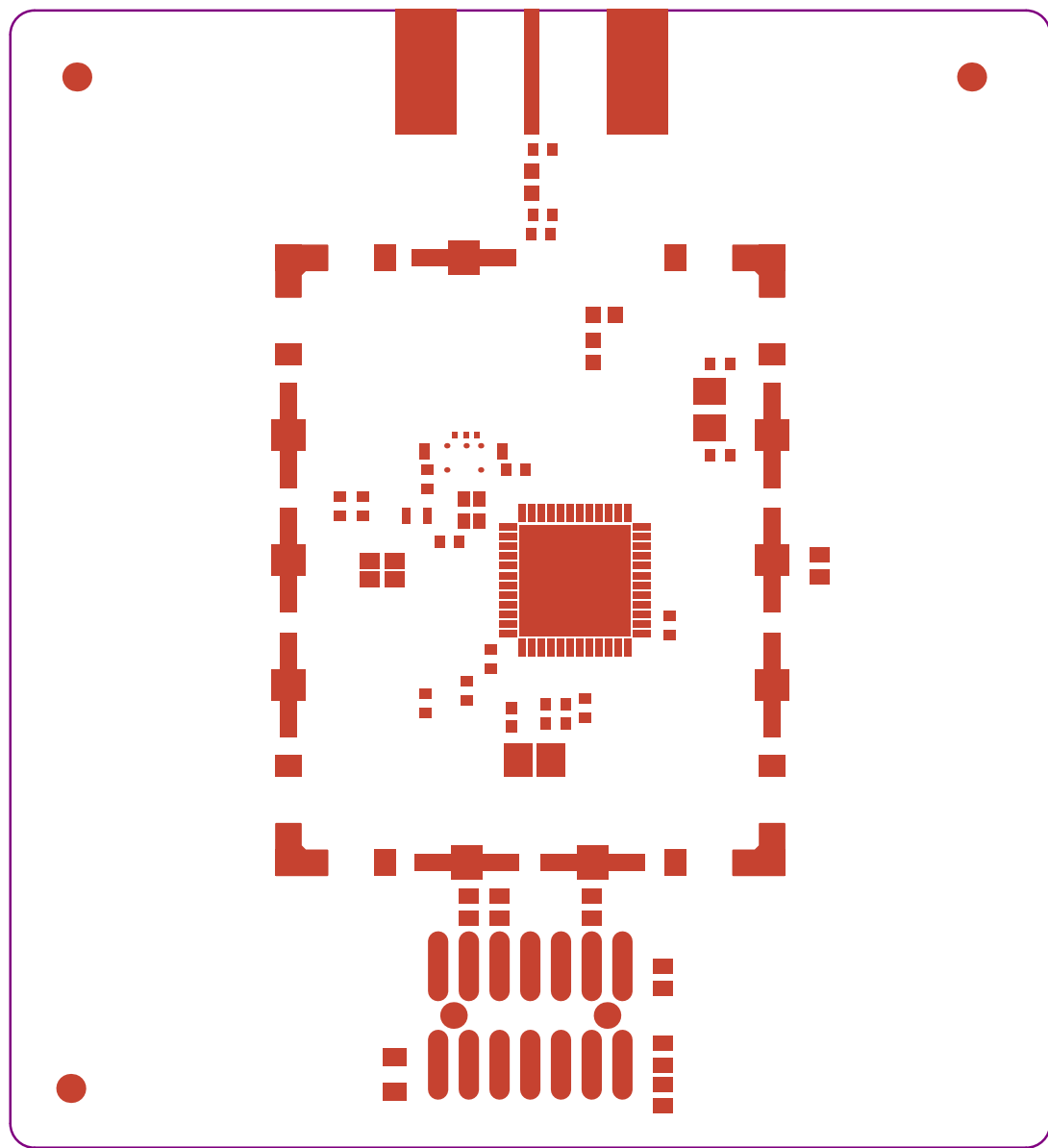
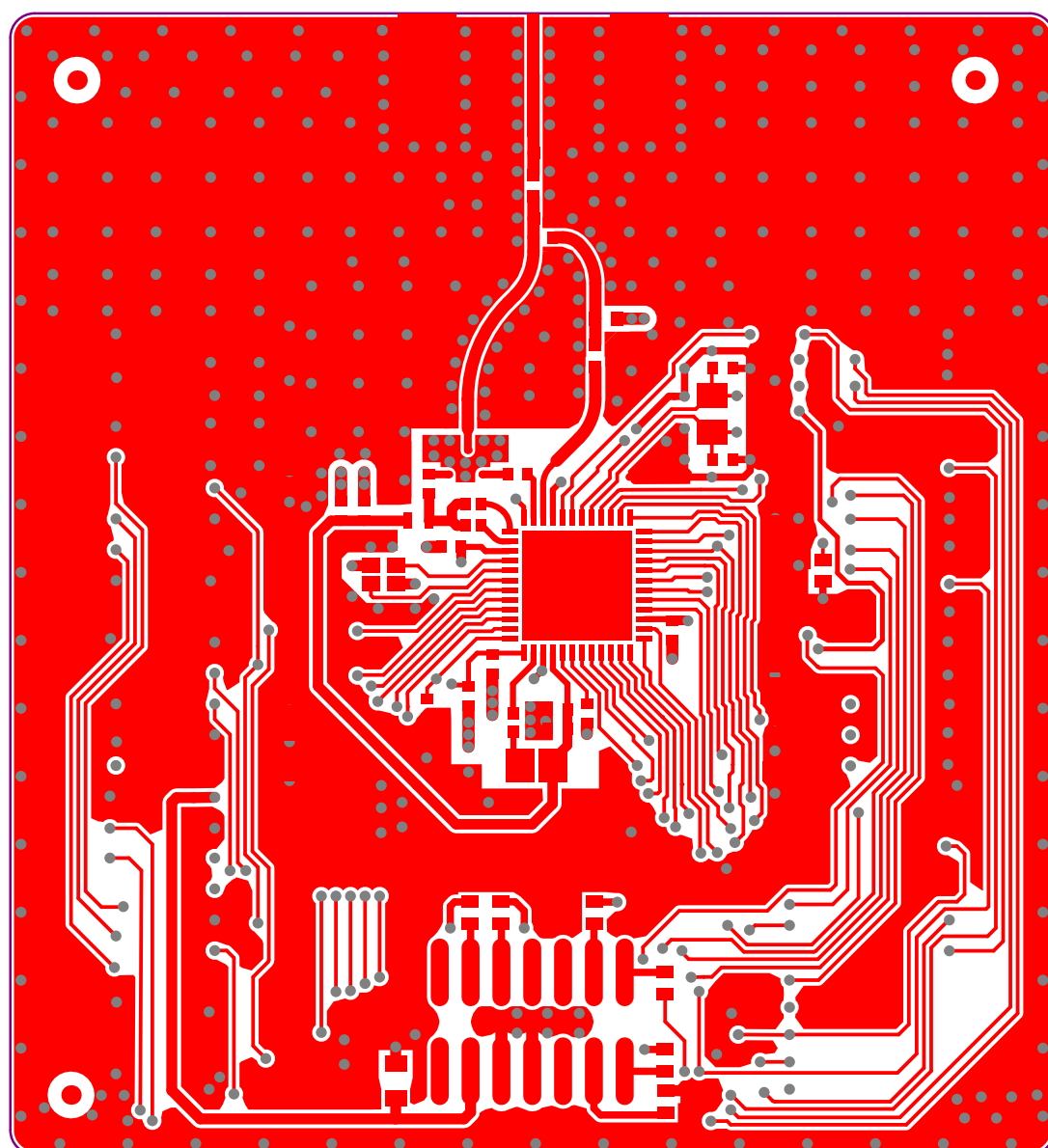




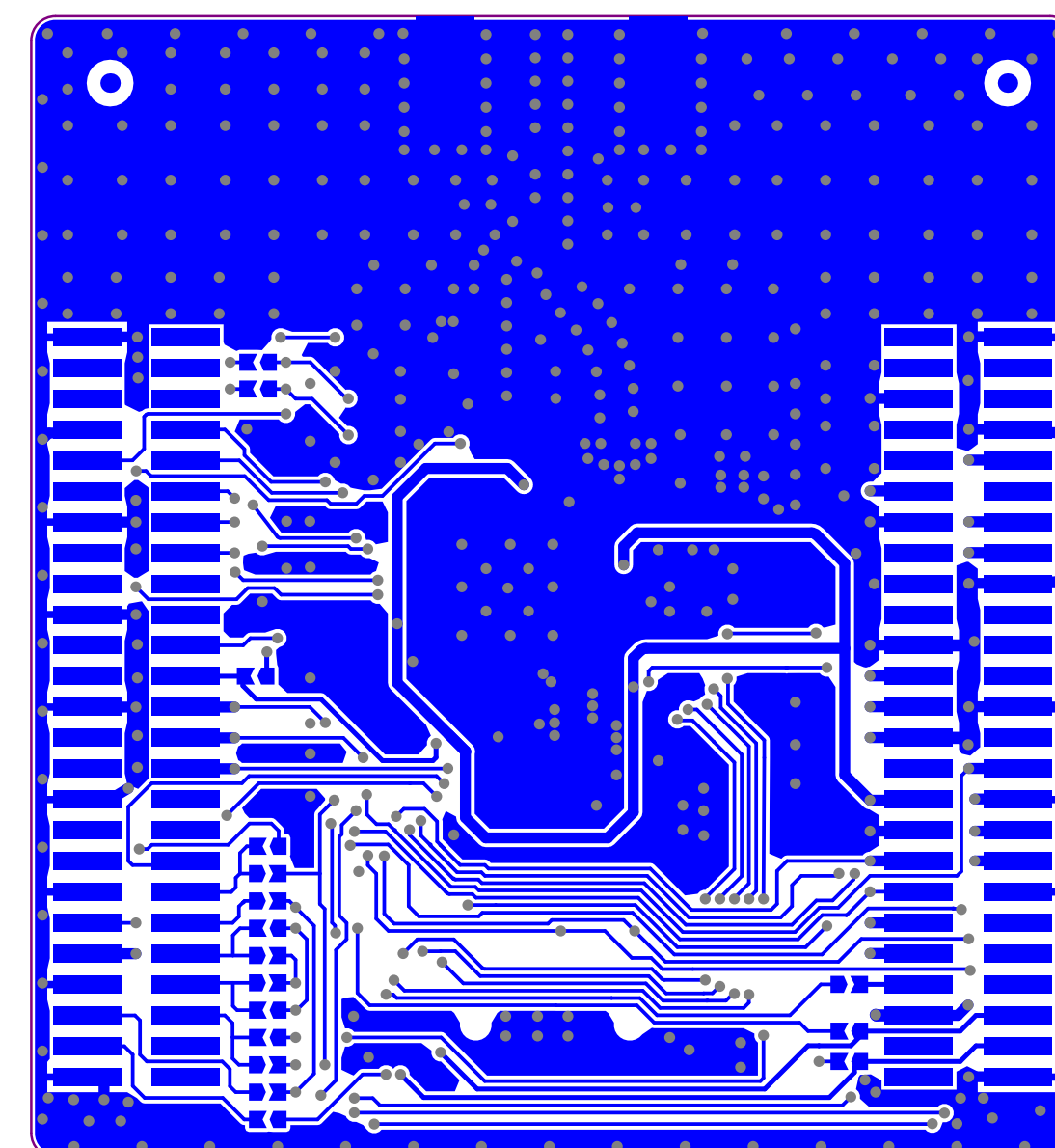
Project: STM32WL3 - QFN48 - 2-Layers - IPD		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2176	
Date: 26/03/2025	Rev: A	



Project: STM32WL3 - QFN48 - 2-Layers - IPD		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2176	
Date: 26/03/2025	Rev: A	

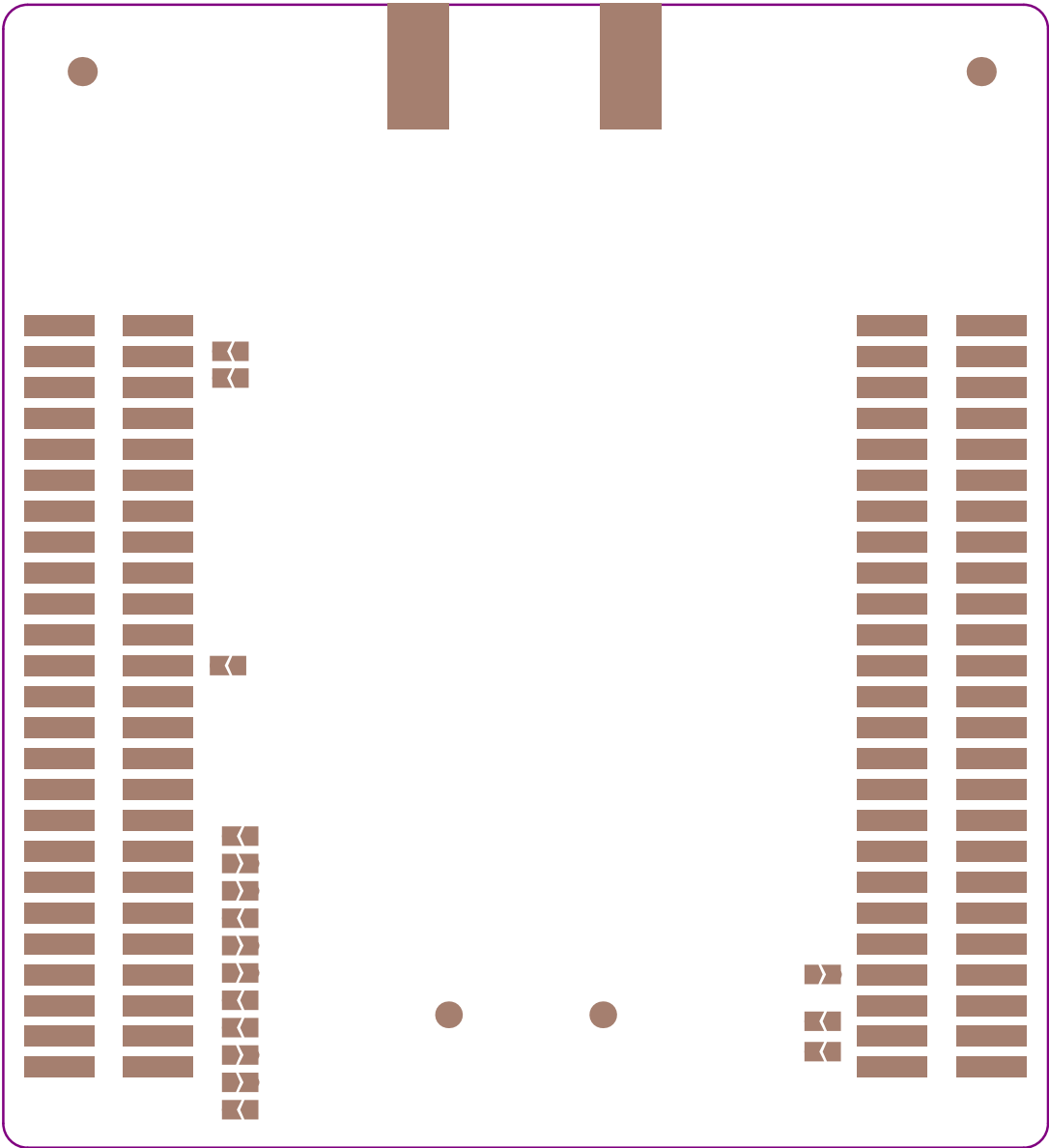


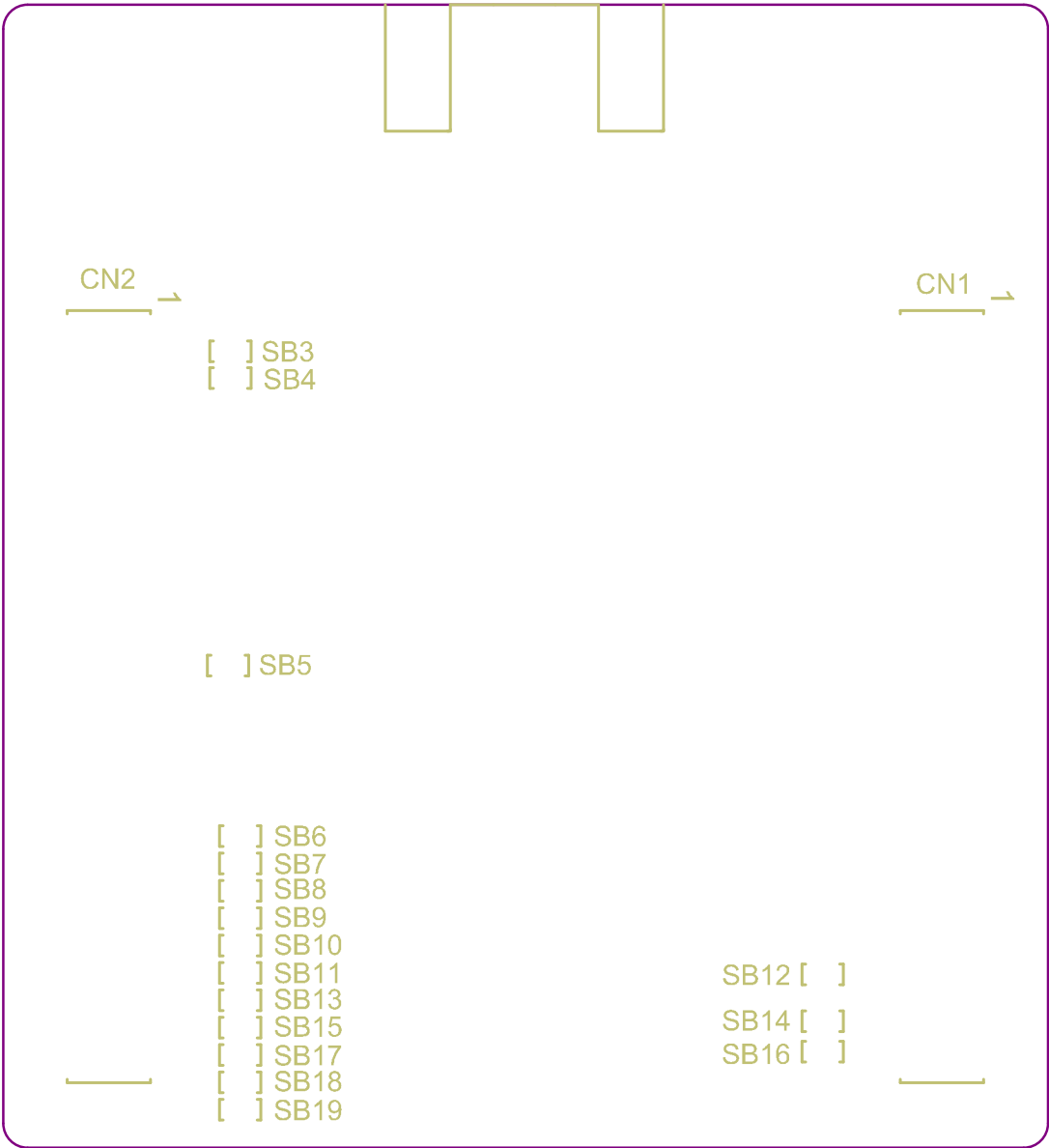
Project: STM32WL3 - QFN48 - 2-Layers - IPD		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2176	
Date: 26/03/2025	Rev: A	



Project: STM32WL3 - QFN48 - 2-Layers - IPD		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB2176	
Date: 26/03/2025	Rev: A	

Project: STM32WL3 - QFN48 - 2-Layers - IPD		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2176	
Date: 26/03/2025	Rev: A	





Project: STM32WL3 - QFN48 - 2-Layers - IPD

Layer: Bottom Overlay

Gerber:.GBO

Variant: [No Variations]

Ref: MB2176

Date: 26/03/2025

Rev: A



PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

VT-47

☐ GREEN

☒ BLUE

☐ WHITE

☐ YELLOW

☐ BLACK

☒ ENIG

☐ IMMERSION SILVER

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ NO

☒ YES

☐ TG-170

☐ TG-150

☒ TG-140

☐ RED

☐ BLACK

☐ IMMERSION TIN

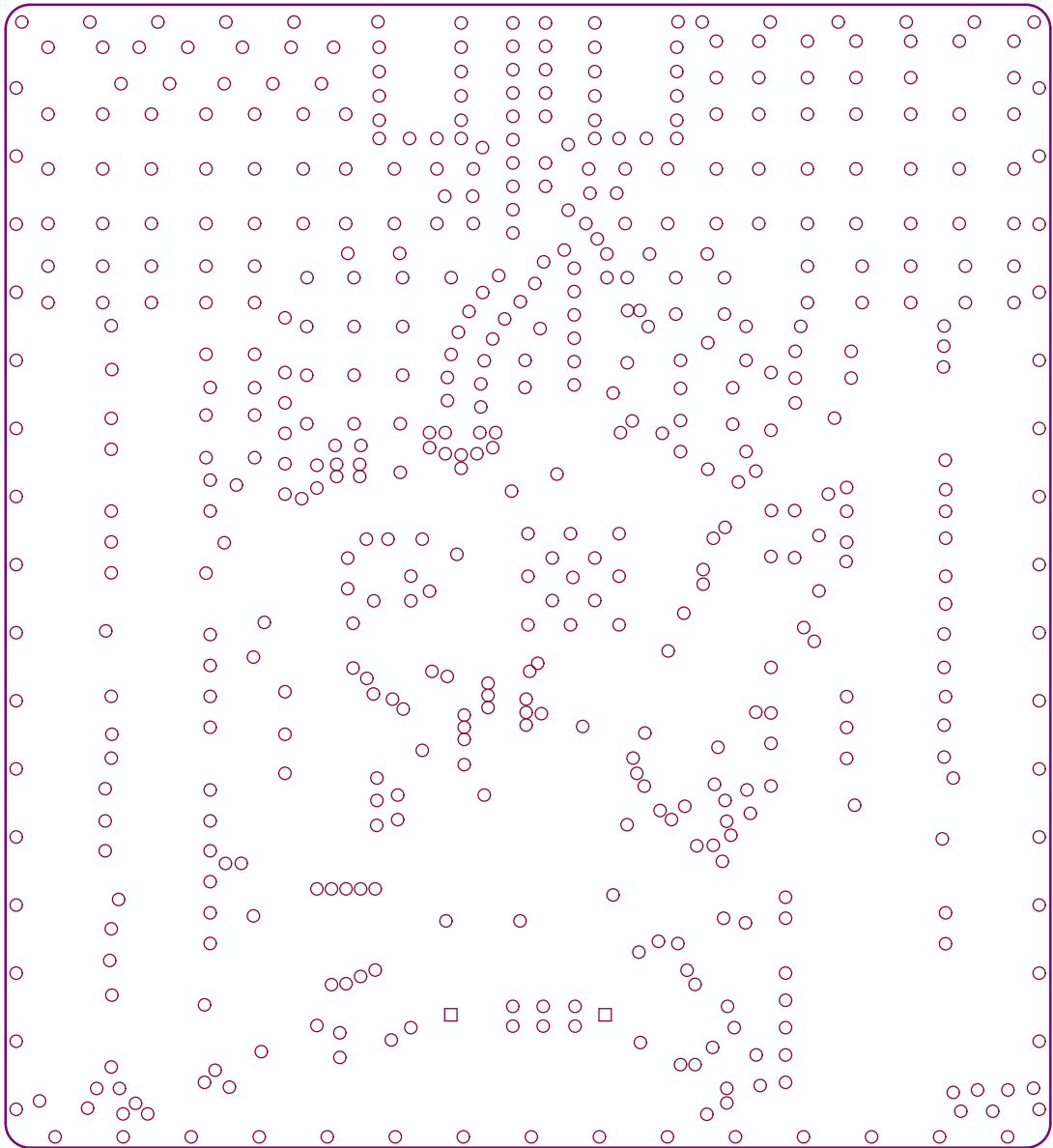
☐ GOLDEN FINGER

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6 :1 à 8 :1
LEVEL "B"



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0.010mm	3.5
1	Top Layer	Copper	0.041mm	
	Dielectric 2	FR4	0.914mm	4.3
2	Bottom Layer	Copper	0.041mm	
	Bottom Solder	Solder Resist	0.010mm	3.5
	Bottom Overlay			

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.150mm
GAPS : 0.150mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length
	549	0.20mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-
	2	1.00mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-
	551 Total						

Project: STM32WL3 - QFN48 - 2-Layers - IPD

Layer: Drill Drawing

Variant: [No Variations]

Date: 26/03/2025

Gerber: .DRL

Ref: MB2176

Rev: A

